ABSTRACT

DIE BONDER INCORPORATING DUAL-HEAD DISPENSER

Adhesive is dispensed for conducting die bonding onto a substrate including rows of bond pads aligned along a first axis and columns of bond pads aligned along a second axis transverse to the first axis where target dispensing positions are located. A first dispensing head incorporating a first nozzle and a second dispensing head incorporating a second nozzle are provided and the substrate is fed along the first axis to a position where the first and second dispensing heads are located. Pattern recognition of a columnar section of the substrate comprising one or more consecutive columns of bond pads with an optical system may be conducted by moving the optical system along the second axis relative to the substrate. Thereafter, the first nozzle and the second nozzle are driven concurrently to dispense adhesive from the first and second nozzles onto the target dispensing positions in the same columnar section of the substrate.

(FIG. 4)